



BUK9605-30A

N-channel TrenchMOS logic level FET

Rev. 03 — 19 April 2011

Product data sheet

1. Product profile

1.1 General description

Logic level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product has been designed and qualified to the appropriate AEC standard for use in automotive critical applications.

1.2 Features and benefits

- AEC Q101 compliant
- Low conduction losses due to low on-state resistance

1.3 Applications

- Automotive and general purpose power switching

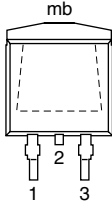
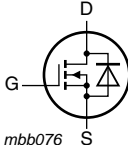
1.4 Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------|--|--|-----|-----|-----|------|
| V_{DS} | drain-source voltage | $T_j \geq 25\text{ °C}; T_j \leq 175\text{ °C}$ | - | - | 30 | V |
| I_D | drain current | $T_{mb} = 25\text{ °C}$ | - | - | 75 | A |
| P_{tot} | total power dissipation | | - | - | 230 | W |
| Static characteristics | | | | | | |
| $R_{DS(on)}$ | drain-source on-state resistance | $V_{GS} = 5\text{ V}; I_D = 25\text{ A}; T_j = 25\text{ °C}$ | - | 4.3 | 5 | mΩ |
| | | $V_{GS} = 10\text{ V}; I_D = 25\text{ A}; T_j = 25\text{ °C}$ | - | 3.9 | 4.6 | mΩ |
| Avalanche ruggedness | | | | | | |
| $E_{DS(AL)S}$ | non-repetitive drain-source avalanche energy | $I_D = 75\text{ A}; V_{sup} \leq 25\text{ V}; R_{GS} = 50\text{ Ω}; V_{GS} = 5\text{ V}; T_{j(init)} = 25\text{ °C}; \text{unclamped}$ | - | - | 500 | mJ |

2. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-----------------------------------|---|---|
| 1 | G | gate |  |  |
| 2 | D | drain ^[1] | | |
| 3 | S | source | | |
| mb | D | mounting base; connected to drain | | |

SOT404 (D2PAK)

[1] It is not possible to make a connection to pin 2.

3. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|-------------|---------|--|---------|
| | Name | Description | Version |
| BUK9605-30A | D2PAK | plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped) | SOT404 |

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------------------------|--|---|-----|-----|------|
| V_{DS} | drain-source voltage | $T_j \geq 25\text{ °C}$; $T_j \leq 175\text{ °C}$ | - | 30 | V |
| V_{DGR} | drain-gate voltage | $R_{GS} = 20\text{ k}\Omega$ | - | 30 | V |
| V_{GS} | gate-source voltage | | -10 | 10 | V |
| I_D | drain current | $T_{mb} = 100\text{ °C}$ | - | 75 | A |
| | | $T_{mb} = 25\text{ °C}$ | - | 75 | A |
| I_{DM} | peak drain current | $T_{mb} = 25\text{ °C}$; pulsed | - | 400 | A |
| P_{tot} | total power dissipation | $T_{mb} = 25\text{ °C}$ | - | 230 | W |
| T_{stg} | storage temperature | | -55 | 175 | °C |
| T_j | junction temperature | | -55 | 175 | °C |
| V_{GSM} | peak gate-source voltage | pulsed; $t_p \leq 50\text{ }\mu\text{s}$ | -15 | 15 | V |
| Source-drain diode | | | | | |
| I_S | source current | $T_{mb} = 25\text{ °C}$ | - | 75 | A |
| I_{SM} | peak source current | pulsed; $T_{mb} = 25\text{ °C}$ | - | 240 | A |
| Avalanche ruggedness | | | | | |
| $E_{DS(AL)S}$ | non-repetitive drain-source avalanche energy | $I_D = 75\text{ A}$; $V_{sup} \leq 25\text{ V}$; $R_{GS} = 50\text{ }\Omega$; $V_{GS} = 5\text{ V}$; $T_{j(init)} = 25\text{ °C}$; unclamped | - | 500 | mJ |

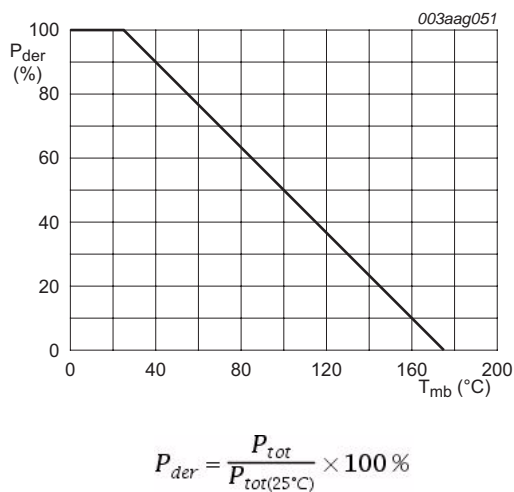


Fig 1. Normalized total power dissipation as a function of mounting base temperature

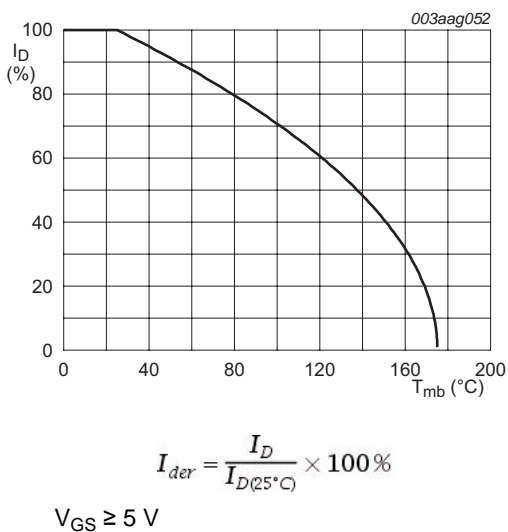


Fig 2. Normalized continuous drain current as a function of mounting base temperature

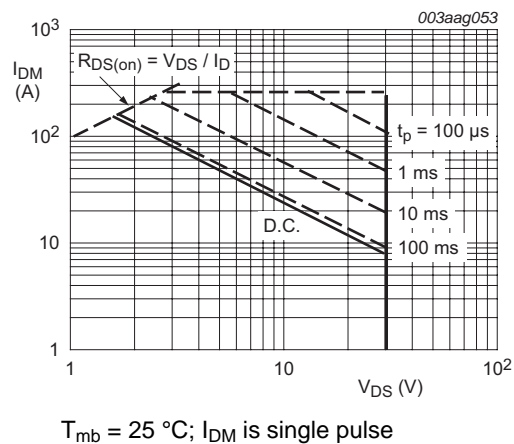


Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

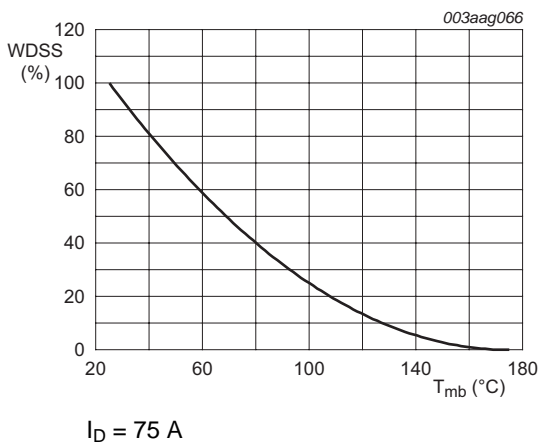


Fig 4. Normalised drain-source non-repetitive avalanche energy as a function of mounting-base temperature

5. Thermal characteristics

Table 5. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|---|-------------------------------|-----|-----|------|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base | | - | - | 0.65 | K/W |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | Minimum footprint ; FR4 board | - | 50 | - | K/W |

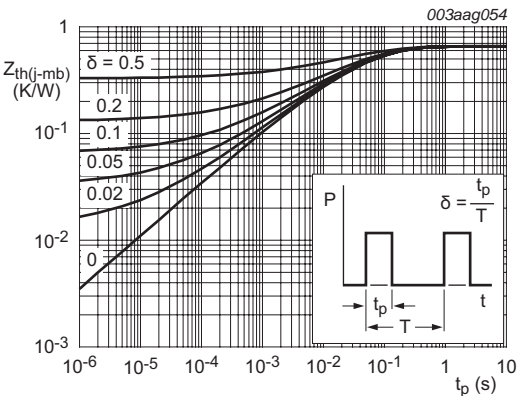


Fig 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

6. Characteristics

Table 6. Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------|----------------------------------|---|-----|------|------|------|
| Static characteristics | | | | | | |
| V _{(BR)DSS} | drain-source breakdown voltage | I _D = 0.25 mA; V _{GS} = 0 V; T _j = 25 °C | 30 | - | - | V |
| | | I _D = 0.25 mA; V _{GS} = 0 V; T _j = -55 °C | 27 | - | - | V |
| V _{GS(th)} | gate-source threshold voltage | I _D = 1 mA; V _{DS} = V _{GS} ; T _j = 25 °C | 1 | 1.5 | 2 | V |
| | | I _D = 1 mA; V _{DS} = V _{GS} ; T _j = 175 °C | 0.5 | - | - | V |
| | | I _D = 1 mA; V _{DS} = V _{GS} ; T _j = -55 °C | - | - | 2.3 | V |
| I _{DSS} | drain leakage current | V _{DS} = 30 V; V _{GS} = 0 V; T _j = 25 °C | - | 0.05 | 10 | μA |
| | | V _{DS} = 30 V; V _{GS} = 0 V; T _j = 175 °C | - | - | 500 | μA |
| I _{GSS} | gate leakage current | V _{GS} = 10 V; V _{DS} = 0 V; T _j = 25 °C | - | 2 | 100 | nA |
| | | V _{GS} = -10 V; V _{DS} = 0 V; T _j = 25 °C | - | 2 | 100 | nA |
| R _{DSon} | drain-source on-state resistance | V _{GS} = 5 V; I _D = 25 A; T _j = 25 °C | - | 4.3 | 5 | mΩ |
| | | V _{GS} = 10 V; I _D = 25 A; T _j = 25 °C | - | 3.9 | 4.6 | mΩ |
| | | V _{GS} = 4.5 V; I _D = 25 A; T _j = 25 °C | - | - | 5.4 | mΩ |
| | | V _{GS} = 5 V; I _D = 25 A; T _j = 175 °C | - | - | 9.3 | mΩ |
| Dynamic characteristics | | | | | | |
| C _{iss} | input capacitance | V _{GS} = 0 V; V _{DS} = 25 V; f = 1 MHz; T _j = 25 °C | - | 6500 | 8600 | pF |
| C _{oss} | output capacitance | V _{GS} = 0 V; V _{DS} = 25 V; f = 1 MHz; T _j = nk °C | - | 1500 | 1800 | pF |
| C _{rss} | reverse transfer capacitance | V _{GS} = 0 V; V _{DS} = 25 V; f = 1 MHz; T _j = 25 °C | - | 1000 | 1350 | pF |
| t _{d(on)} | turn-on delay time | V _{DS} = 30 V; R _L = 1.2 Ω; V _{GS} = 5 V; R _{G(ext)} = 10 Ω; T _j = 25 °C | - | 45 | 65 | ns |
| t _r | rise time | | - | 220 | 330 | ns |
| t _{d(off)} | turn-off delay time | | - | 435 | 600 | ns |
| t _f | fall time | | - | 320 | 450 | ns |
| L _D | internal drain inductance | measured from upper edge of drain tab to centre of die ; T _j = 25 °C | - | 2.5 | - | nH |
| L _S | internal source inductance | from source lead soldering point to source bond pad ; T _j = 25 °C | - | 7.5 | - | nH |
| Source-drain diode | | | | | | |
| V _{SD} | source-drain voltage | I _S = 25 A; V _{GS} = 0 V; T _j = 25 °C | - | 0.85 | 1.2 | V |
| | | I _S = 75 A; V _{GS} = 0 V; T _j = 25 °C | - | 1.1 | - | V |
| t _{rr} | reverse recovery time | I _S = 75 A; dI _S /dt = -100 A/μs; | - | 400 | - | ns |
| Q _r | recovered charge | V _{GS} = -10 V; V _{DS} = 30 V; T _j = 25 °C | - | 1 | - | μC |

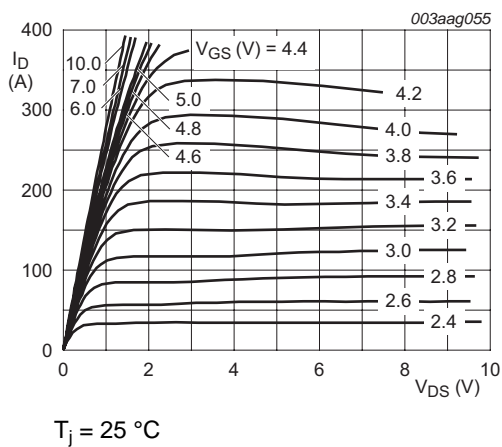


Fig 6. Output characteristics: drain current as a function of drain-source voltage; typical values

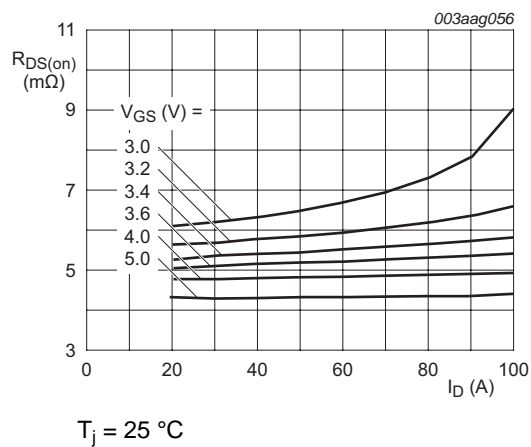


Fig 7. Drain-source on-state resistance as a function of drain current; typical values

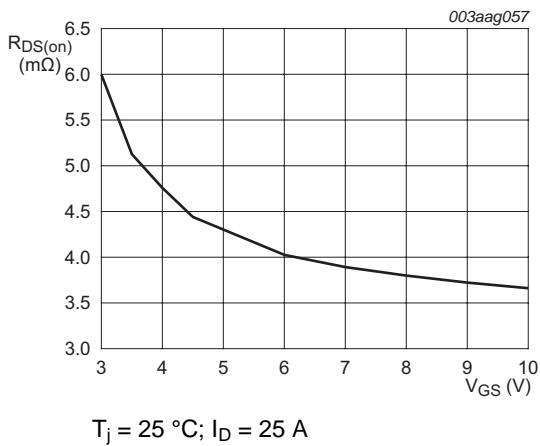


Fig 8. Drain-source on-state resistance as a function of gate-source voltage; typical values

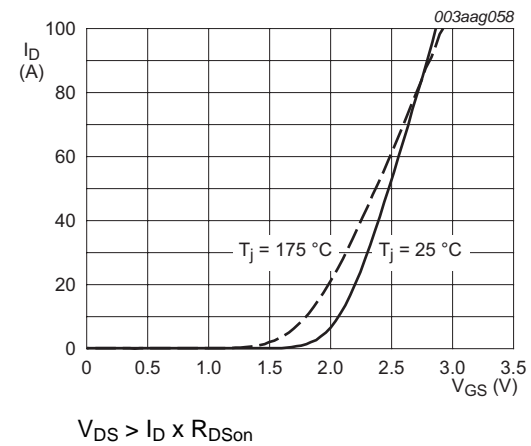


Fig 9. Transfer characteristics: drain current as a function of gate-source voltage; typical values

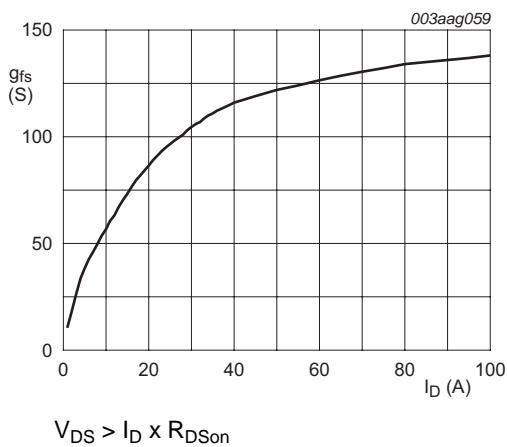


Fig 10. Forward transconductance as a function of drain current; typical values

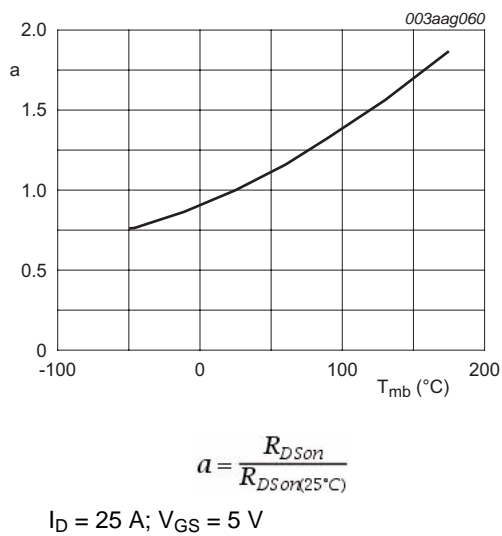


Fig 11. Normalized drain-source on-state resistance factor as a function of junction temperature

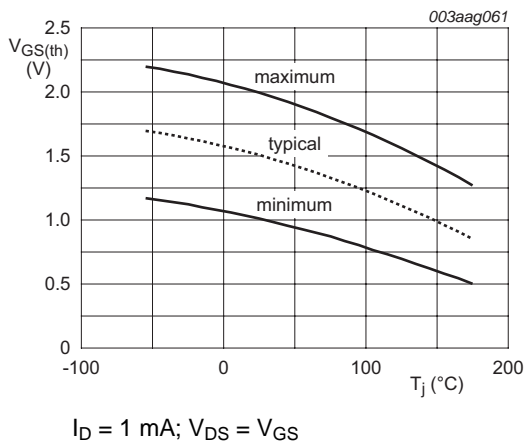


Fig 12. Gate-source threshold voltage as a function of junction temperature

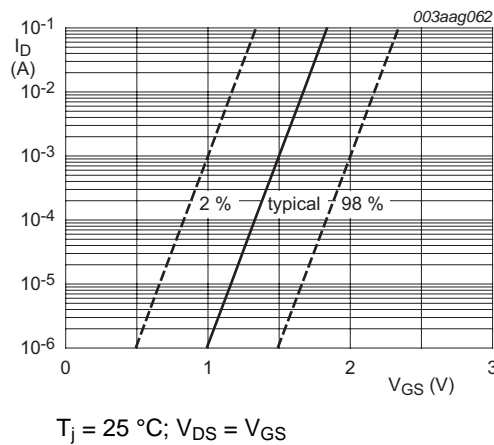


Fig 13. Sub-threshold drain current as a function of gate-source voltage

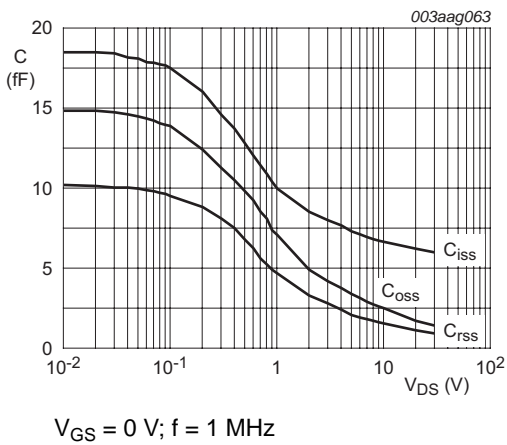


Fig 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

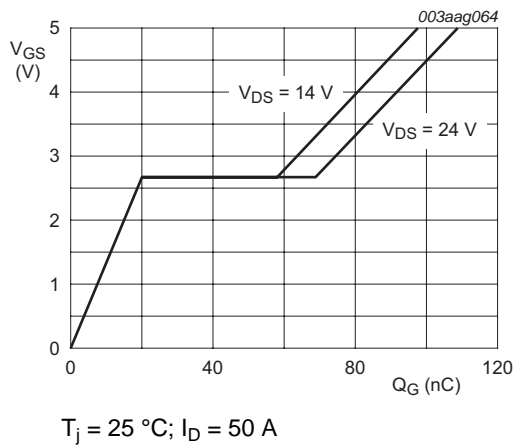


Fig 15. Gate-source voltage as a function of gate charge; typical values

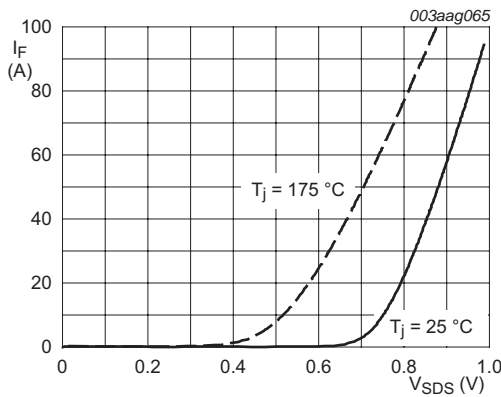
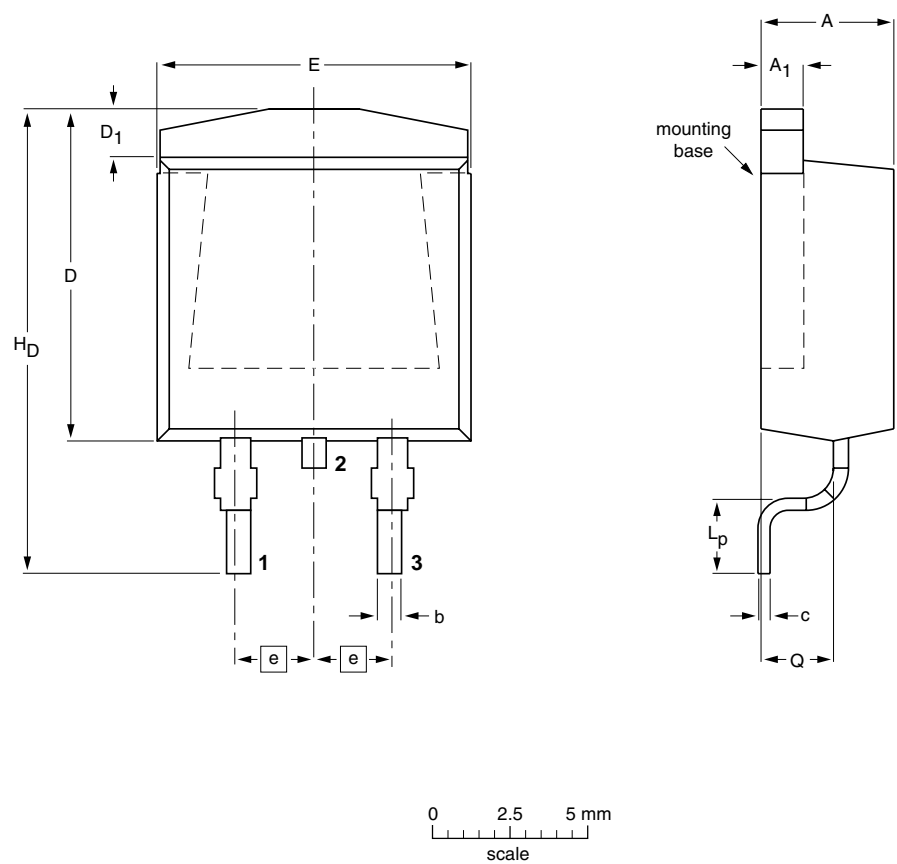


Fig 16. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values

7. Package outline

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)

SOT404



DIMENSIONS (mm are the original dimensions)

| UNIT | A | A ₁ | b | c | D _{max.} | D ₁ | E | e | L _p | H _D | Q |
|------|--------------|----------------|--------------|--------------|-------------------|----------------|---------------|------|----------------|----------------|--------------|
| mm | 4.50 4.10 | 1.40 1.27 | 0.85 0.60 | 0.64 0.46 | 11 | 1.60 1.20 | 10.30 9.70 | 2.54 | 2.90 2.10 | 15.80 14.80 | 2.60 2.20 |


| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|--------------------|------------|-------|-------|--|---|----------------------|
| | IEC | JEDEC | JEITA | | | |
| SOT404 | | | | |  | 05-02-11 06-03-16 |

Fig 17. Package outline SOT404 (D2PAK)

8. Revision history

Table 7. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|-----------------|--|-----------------------|---------------|-----------------|
| BUK9605-30A v.3 | 20110419 | Product data sheet | - | BUK9605-30A v.2 |
| Modifications: | <ul style="list-style-type: none">• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.• Legal texts have been adapted to the new company name where appropriate. | | | |
| BUK9605-30A v.2 | 19990801 | Product specification | - | BUK9605-30A v.1 |

9. Legal information

9.1 Data sheet status

| Document status ^{[1] [2]} | Product status ^[3] | Definition |
|------------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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